



WANSEMI
万芯半导体

WX016N08KF

Enhancement Mode N-Channel Power MOSFET

TO-263/NMOS/80V/ ± 20 V/3.0V/246A/1.9m Ω

Rev0.6

80V, 1.9mΩ, 246A, N-Channel Enhancement MOSFET

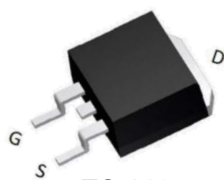
1.Features

- ◆ 80V MOSFET technology
- ◆ Low on-state resistance
- ◆ Fast switching
- ◆ $V_{GS} \pm 20V$
- ◆ 100% RG Tested
- ◆ 100% UIS Tested

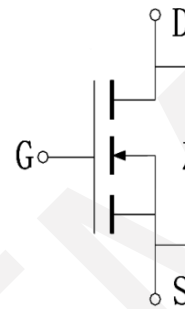
V_{DS}	$R_{DS(on)}$ Typ.	I_D Max.
80V	1.9mΩ @ 10V	246A

2.Applications

- ◆ Power Switching Application
- ◆ Load Switching



TO-263
Pin Description



Schematic Diagram

3.Package Marking and Ordering Information

Part no.	Marking	Package	PCS/Reel	PCS/CTN.
WX016N08KF	016N08	TO-263	800	4,800

4.Absolute Max Ratings at $T_a=25^\circ C$ (Note1)

Parameter	Symbol	Maximum	Units
Drain to Source Voltage	V_{DSS}	80	V
Gate to Source Voltage	V_{GSS}	± 20	V
Drain Current (DC)	I_D	246	A
Drain Current (Pulse), $PW \leq 300\mu s$	I_{DP}	984	A
Total Dissipation	P_D	310	W
Avalanche Energy, Single Pulsed	E_{AS}	1600	mJ
Junction Temperature	T_j	150	$^\circ C$
Storage Temperature	T_{stg}	-55 to +150	$^\circ C$

Note 1: Stresses exceeding those listed in the Maximum Ratings table may damage the device. If any of these limits are exceeded, device functionality should not be assumed, damage may occur and reliability may be affected.

5. Thermal Resistance Ratings

Parameter	Symbol	Value	Unit
Junction to Case	$R_{\theta JC}$	0.4	$^{\circ}C/W$

Note 2: When mounted on 1 inch square copper board $t \leq 10$ sec The value in any given application depends on the user's specific board design.

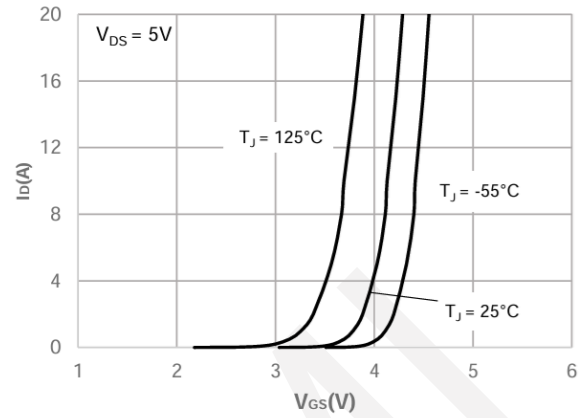
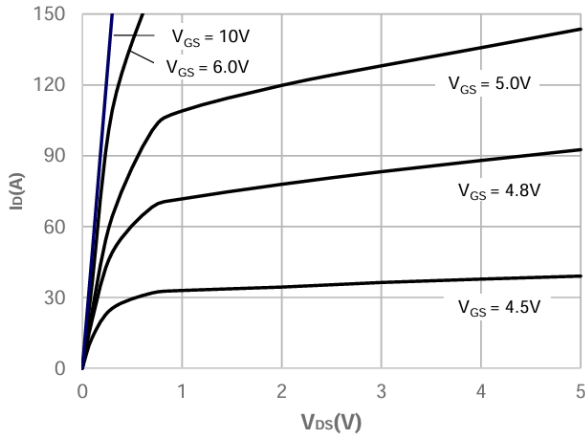
6. Electrical Characteristics at $T_a=25^{\circ}C$ (Note 3)

Parameter	Symbol	Test Conditions	Min.	Typ.	Max.	Units
Drain to Source Breakdown Voltage	$V_{(BR)DSS}$	$I_D = 250\mu A, V_{GS} = 0V$	80	-	-	V
Zero-Gate Voltage Drain Current	I_{DSS}	$V_{DS} = 80V, V_{GS} = 0V$	-	-	1	μA
Gate to Source Leakage Current	I_{GSS}	$V_{GS} = \pm 20V, V_{DS} = 0V$	-	-	± 100	nA
Gate Threshold Voltage	$V_{GS(th)}$	$V_{DS} = V_{GS}, I_{DS} = 250\mu A$	2.4	3.0	3.8	V
Static Drain to Source On-State Resistance	$R_{DS(on)}$	$I_D = 20A, V_{GS} = 10V$	-	1.9	2.4	$m\Omega$
Input Capacitance	C_{iss}	$V_{GS} = 0V,$ $V_{DS} = 40V,$ Frequency = 1.0MHz	-	8228	-	nF
Output Capacitance	C_{oss}		-	2935	-	pF
Reverse Transfer Capacitance	C_{rss}		-	121	-	pF
Turn-ON Delay Time	$t_{d(on)}$		-	36	-	ns
Rise Time	t_r	$V_{DS} = 40V, V_{GS} = 10V,$ $I_D = 20A, R_{GEN} = 6.2\Omega$	-	38	-	ns
Turn-OFF Delay Time	$t_{d(off)}$		-	87	-	ns
Fall Time	t_f		-	43	-	ns
Total Gate Charge	Q_g	$V_{DS} = 40V,$ $V_{GS} = 0$ to 10V, $I_D = 20A$	-	128	-	nC
	Q_{gs}		-	40	-	nC
	Q_{gd}		-	26	-	nC
Diode Forward Voltage	V_{FSD}	$I_S = 20A, V_{GS} = 0$	-	-	1.2	V

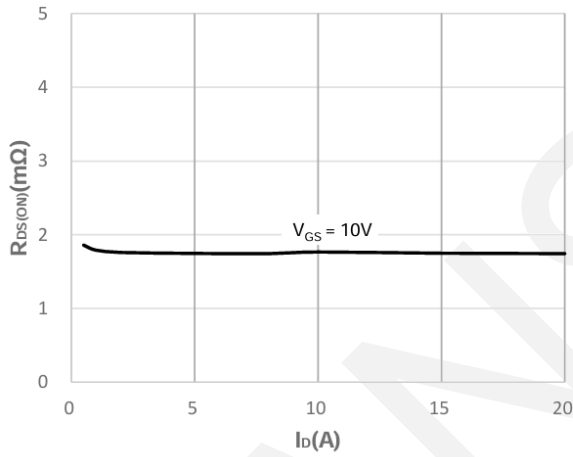
Note 3: Product parametric performance is indicated in the Electrical Characteristics for the listed test conditions, unless otherwise noted. Product performance may not be indicated by the Electrical Characteristics if operated under different conditions.



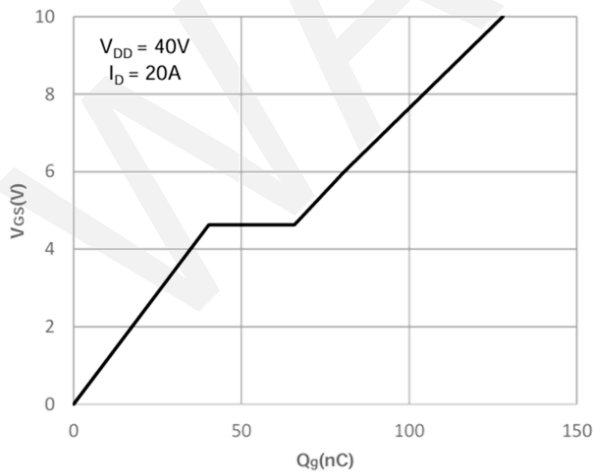
7. Typical electrical and thermal characteristics



Output Characteristics

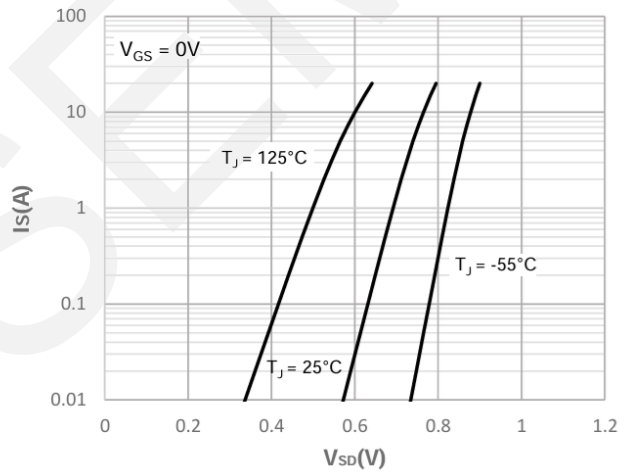


On-resistance vs. Drain Current

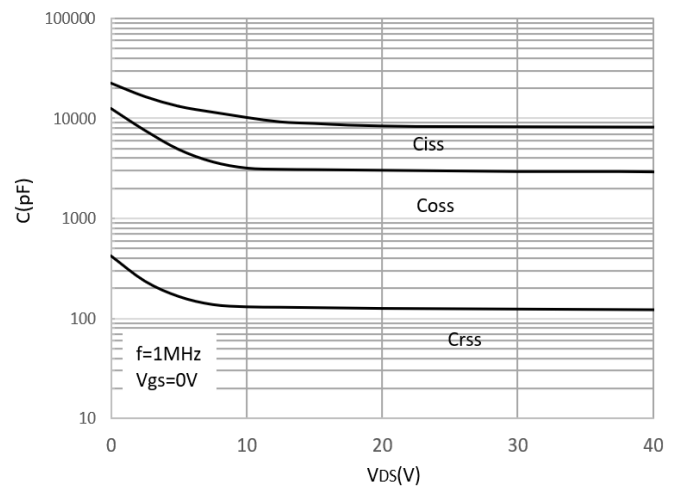


Gate Charge Characteristics

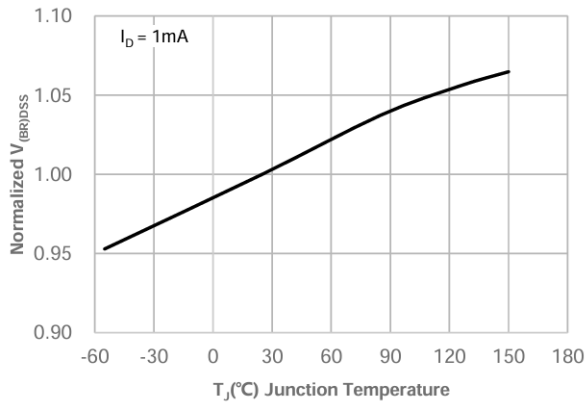
Typical Transfer Characteristics



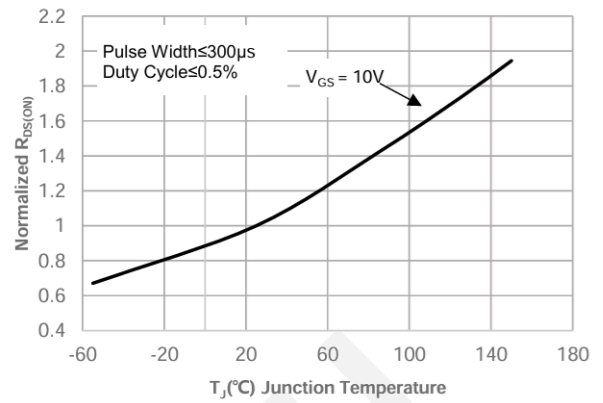
Body Diode Characteristics



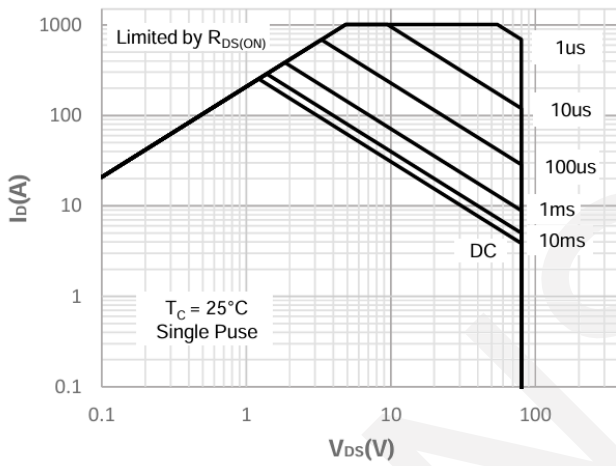
Capacitance Characteristics



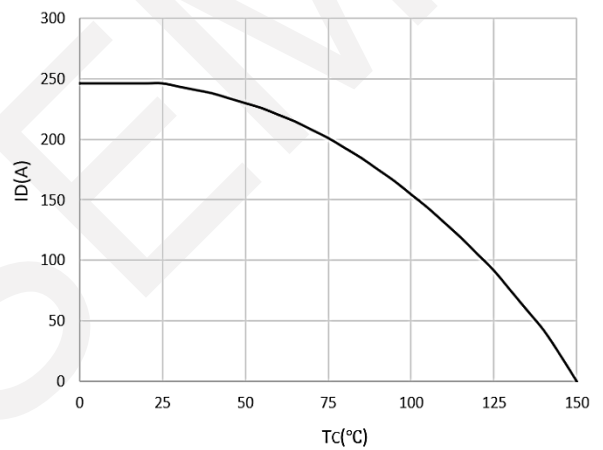
Normalized Breakdown Voltage vs. Junction Temperature



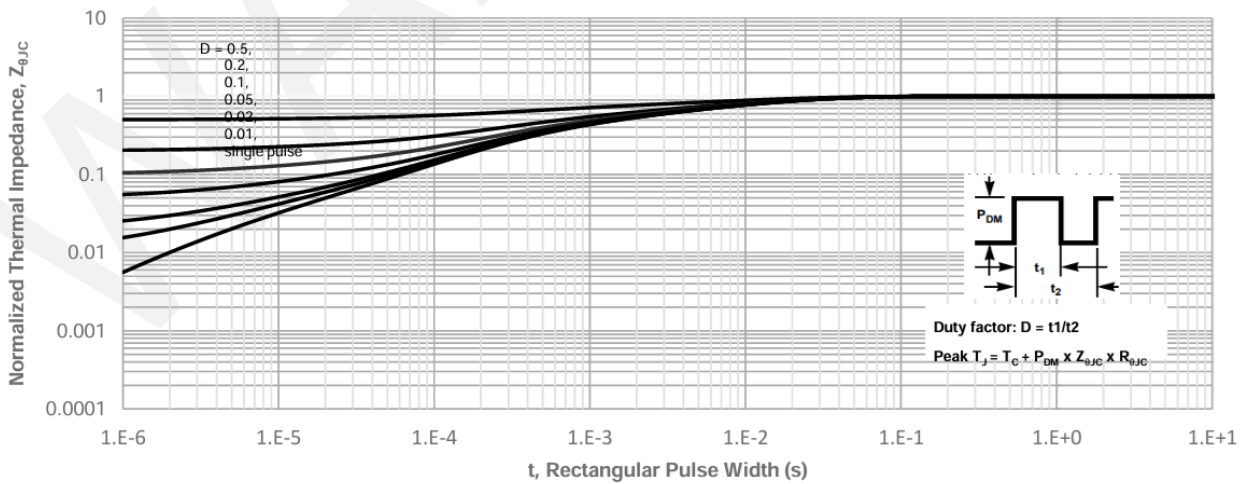
Normalized on Resistance vs. Junction Temperature



Maximum Safe Operating Area



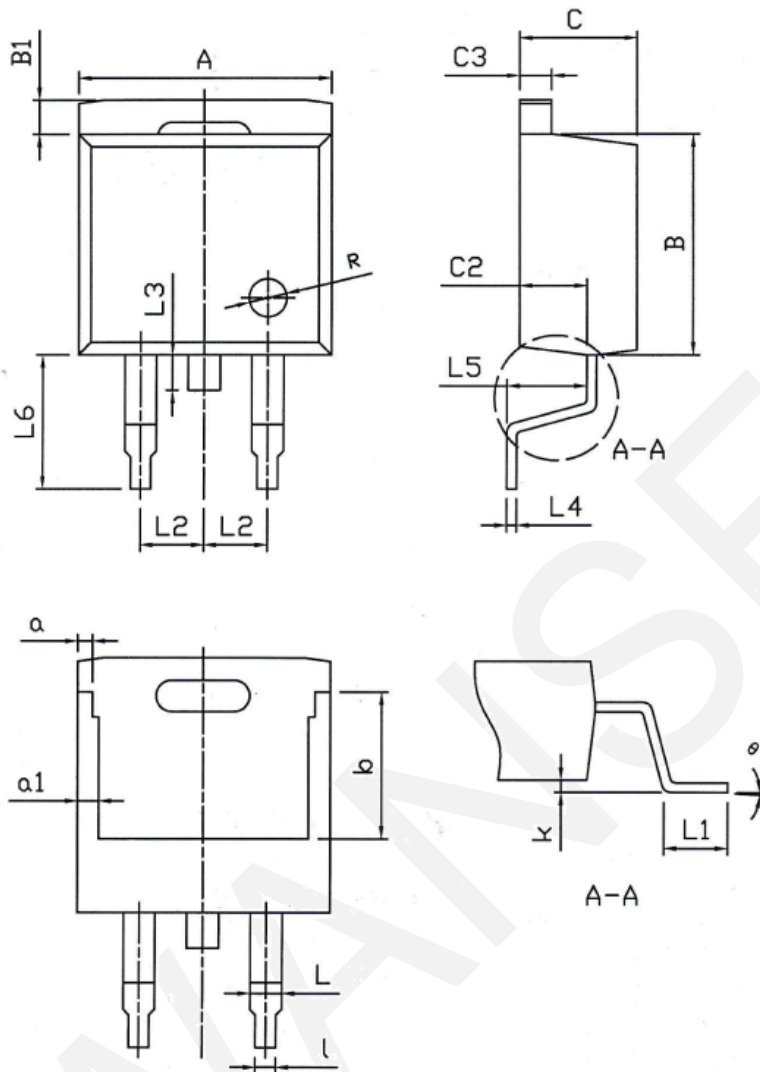
Maximum Continuous Drain Current vs. Case Temperature



Maximum Effective Transient Thermal Impedance, Junction-to-Case



8.Package Dimensions



Dimensions In Millimeters			
Symbol	MIN	TYP	MAX
A	10.00	10.20	10.40
B	8.50	8.70	8.90
B1	1.06	1.26	1.46
C	4.49	4.69	4.89
C2	2.54	2.69	2.84
C3	1.17	1.27	1.37
L	1.12	1.27	1.42
L1	2.34	2.54	2.74
L2	-	2.54	-
L3	1.20	1.40	1.60
L4	0.281	0.381	0.481
L5	2.54	2.79	3.04
L6	5.05	5.30	5.55
R	-	1.50	-
a	0.455	0.655	0.855
a1	0.70	0.90	1.10
b	5.648	5.798	5.948
k	0.00	-	0.25
l	0.70	0.81	0.96
theta	0°	-	9°

9. Important Notice

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